

REMARKS/ARGUMENTS

In the specification, paragraph [0003] has been amended to correct minor editorial problems. No new matter has been added.

The Office Action mailed April 26, 2004, has been received and reviewed. Claims 1 through 18 are currently pending in the application. Claims 1 through 6, and 11 through 18 are allowed. Claims 7 through 10 stand rejected.

Per this response, Applicants have amended claims 1, 7, 9-13, and 18, added new claims 19 and 20, and respectfully request reconsideration of the application as amended herein and in view of the arguments set forth below.

35 U.S.C. § 102 Anticipation Rejections

Anticipation Rejection Based on U.S. Patent No. 6,405,359 to Tseng et al.

Claim 7 stands rejected under 35 U.S.C. § 102(e) as being anticipated by Tseng et al. (U.S. Patent No. 6,405,359). Applicants respectfully traverse this rejection, as hereinafter set forth.

A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference. *Verdegaal Brothers v. Union Oil Co. of California*, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989).

Tseng discloses a method for conducting backside failure analysis on a wafer. A plurality of conductive metal strips 36, 38, 40, and 42 are adhesively bonded on the active surface 48 of the wafer. A plurality of lead wires 60 are wire bonded for establishing electrical communication between the plurality of metal strips 36, 38, 40, and 42 and a plurality of corresponding bond pads 50 on the wafer surface, respectively. (See, e.g., col. 6, lines 18-26).

Presently amended independent claim 7 recites, "A semiconductor die assembly, comprising: a semiconductor die having a plurality of bond pads; a lead frame having a plurality of conductive leads, *each conductive lead being electrically coupled* at spaced locations on the

conductive lead *to at least two bond pads* of the plurality of bond pads.” (emphasis added). Tseng fails to disclose *each* conductive lead of a plurality electrically *coupled to at least two* bond pads. Rather, Tseng discloses electrical communication between individual conductive metal strips and individual bond pads, *respectively*. Accordingly, Tseng fails to describe each and every element of presently amended claim 7. Therefore, it is respectfully submitted that the rejection to claim 7 should be withdrawn.

Anticipation Rejection Based on U.S. Patent No. 5,714,800 to Thompson

Claims 7 through 10 stand rejected under 35 U.S.C. § 102(b) as being anticipated by Thompson (U.S. Patent No. 5,714,800). Applicants respectfully traverse this rejection, as hereinafter set forth.

Thompson recites a method of forming an integrated circuit assembly. IC die 200 comprises a plurality of bonding pads 210 and has a stepped interposer 300 disposed over a central region of the IC die 200. (Col. 3, lines 18-20). Stepped interposer 300 comprises bonding region or bonding area 350. (Col.3, lines 52-53). IC die 200 is electrically coupled to stepped interposer 300 through bonding wire 400. (Col. 3, lines 62-63). Some of the bonding pads 210 are electrically coupled to some of the bonding regions 350. (Abstract). Figure 3 is a cross sectional view of an integrated circuit assembly showing one bonding pad 210 electrically coupled to one bonding region 350 through one bonding wire 400.

Presently amended independent claim 7 recites, “A semiconductor die assembly, comprising: a semiconductor die having a plurality of bond pads; *a lead frame having a plurality of conductive leads, each conductive lead being electrically coupled at spaced locations on the conductive lead to at least two bond pads* of the plurality of bond pads.” (emphasis added). Thompson fails to disclose a lead frame having a plurality of conductive leads. Thompson further fails to disclose a conductive lead electrically coupled at spaced locations on the conductive lead to at least two bond pads of a semiconductor die. Rather, Thompson describes bonding wire electrically coupling *one bonding pad of an IC die to one bonding region of a stepped interposer*.

Accordingly, Thompson fails to describe each and every element of presently amended claim 7. Therefore, it is respectfully submitted that the rejection to claim 7 should be withdrawn.

Claims 8-10 are each allowable, among other reasons, as depending from claim 7 which should be allowed.

Claim 9 is additionally allowable because Thompson fails to disclose a wire bond coupling each conductive lead at the spaced locations thereon to one of the at least two bond pads of the plurality of bond pads. Rather, Thompson discloses a bond wire electrically coupling one bonding pad of an IC die to one bonding region of a stepped interposer.

Claim 10 is additionally allowable because Thompson fails to disclose a conductive lead including a severance region configured to facilitate separation thereof into at least two mutually electrically isolated conductive elements.

ENTRY OF AMENDMENTS

The amendments to claims 1, 7, 9-13, and 18 above should be entered by the Examiner because the amendments are supported by the as-filed specification and drawings and do not add any new matter to the application.

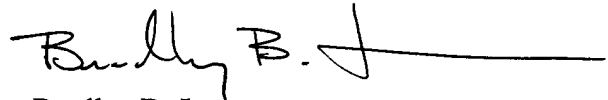
ENTRY OF NEW CLAIMS

New claims 19 and 20 should be entered by the Examiner because the claims are supported by the as-filed specification and drawings and do not add any new matter to the application.

CONCLUSION

Claims 1 through 20 are believed to be in condition for allowance, and an early notice thereof is respectfully solicited. Should the Examiner determine that additional issues remain which might be resolved by a telephone conference, he is respectfully invited to contact Applicants' undersigned attorney.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Bradley B. Jensen", followed by a long horizontal line extending to the right.

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